

SOT751-1

plastic low profile fine-pitch ball grid array package; 80 balls;
body 7 x 7 x 1.05 mm

8 February 2016

Package information

1. Package summary

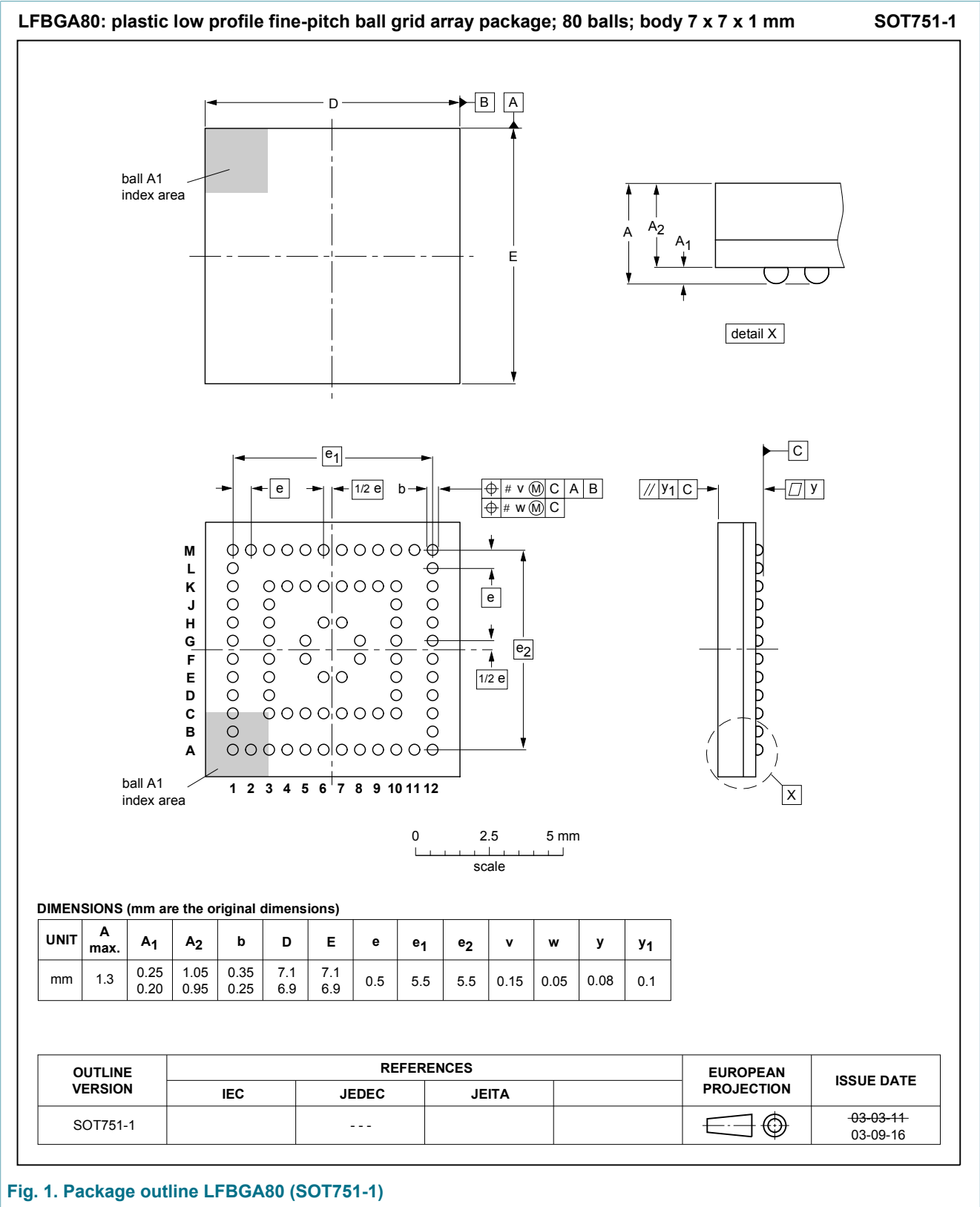
Terminal position code	B (bottom)
Package type descriptive code	LFBGA80
Package type industry code	LFBGA80
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-9-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		6.9	-	7	7.1	mm
E	package width		6.9	-	7	7.1	mm
A	seated height		[tbd]	-	1.3	1.3	mm
A ₂	package height		0.95	-	1.05	1.05	mm
n ₂	actual quantity of termination		-	-	80	-	



2. Package outline



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3. Soldering

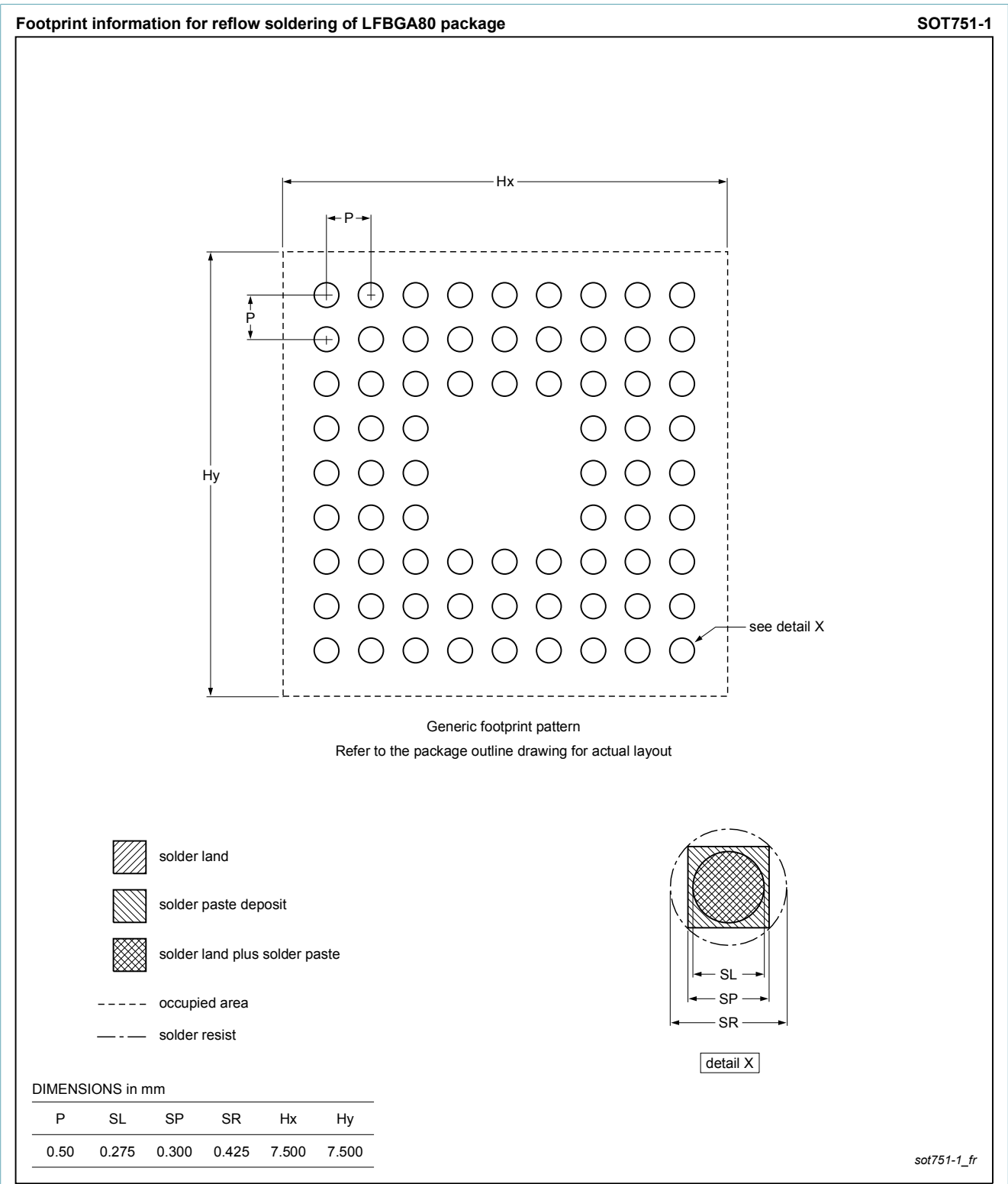


Fig. 2. Reflow soldering footprint for LFBGA80 (SOT751-1)

4. Legal information

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Date of release: 8 February 2016